



Material Content Data Sheet



Sales Product Name		BTS442E2		Issued		22. January 2018		
MA#		MA001790320						
Package		PG-TO220-5-11		Weight*		2115.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	20.863	0.99	0.99	9862	9862
leadframe	non noble metal	iron	7439-89-6	0.923	0.04		436	
	inorganic material	phosphorus	7723-14-0	0.277	0.01		131	
	non noble metal	copper	7440-50-8	921.567	43.55	43.60	435645	436212
	non noble metal	aluminium	7429-90-5	15.938	0.75	0.75	7534	7534
wire	non noble metal	aluminium	7429-90-5	15.938	0.75	0.75	7534	7534
encapsulation	organic material	carbon black	1333-86-4	5.834	0.28		2758	
	inorganic material	antimonytrioxide	1309-64-4	12.198	0.58		5766	
	plastics	brominated resin	-	13.789	0.65		6518	
	plastics	epoxy resin	-	100.765	4.76		47634	
	inorganic material	silicondioxide	60676-86-0	397.755	18.80	25.07	188027	250703
leadfinish	non noble metal	tin	7440-31-5	24.484	1.16	1.16	11574	11574
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		4	
	non noble metal	nickel	7440-02-0	3.285	0.16	0.16	1553	1557
glue	plastics	Polyimide	26023-21-2	0.733	0.03	0.03	347	347
solder	noble metal	silver	7440-22-4	0.169	0.01		80	
	non noble metal	tin	7440-31-5	0.135	0.01		64	
	non noble metal	lead	7439-92-1	6.453	0.31	0.33	3051	3195
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		279	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		84	
	non noble metal	copper	7440-50-8	589.466	27.87	27.91	278653	279016
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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